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### Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

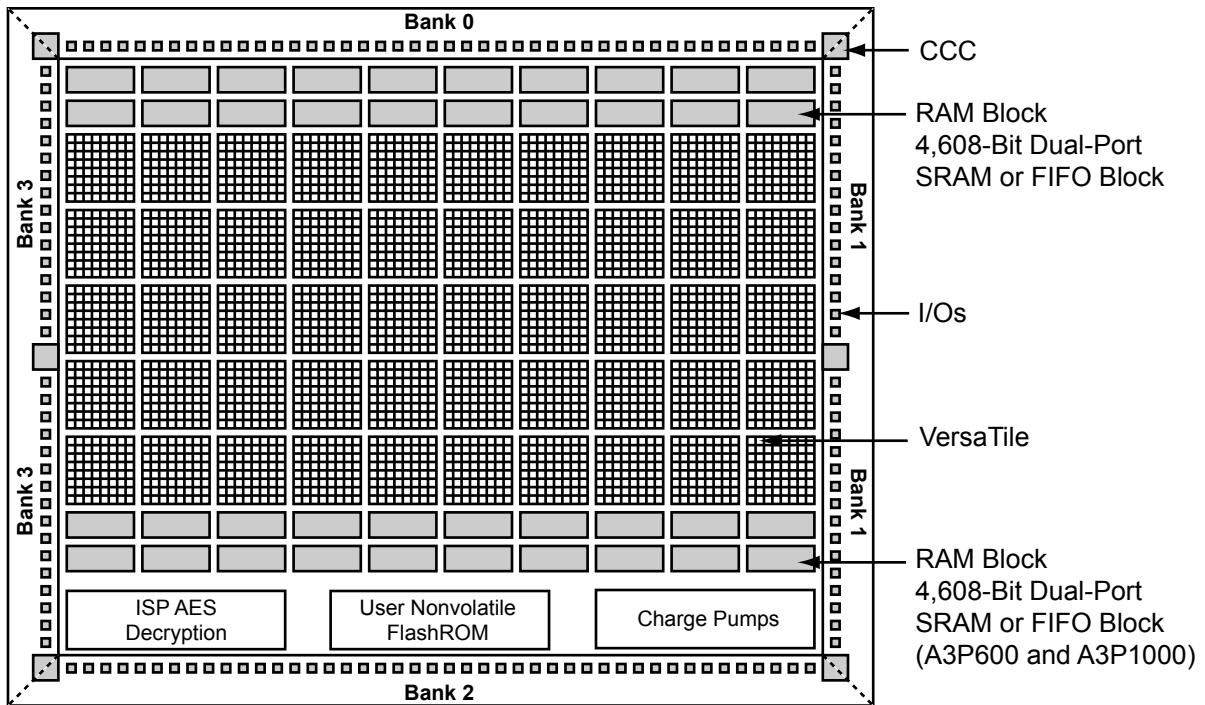
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### **Details**

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	151
Number of Gates	400000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/a3p400-1pq208i">https://www.e-xfl.com/product-detail/microchip-technology/a3p400-1pq208i</a>



**Figure 1-2 • ProASIC3 Device Architecture Overview with Four I/O Banks (A3P250, A3P600, and A3P1000)**

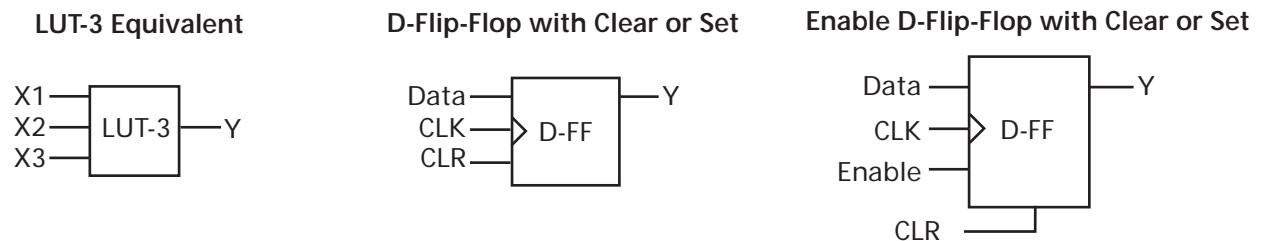
The FPGA core consists of a sea of VersaTiles. Each VersaTile can be configured as a three-input logic function, a D-flip-flop (with or without enable), or a latch by programming the appropriate flash switch interconnections. The versatility of the ProASIC3 core tile as either a three-input lookup table (LUT) equivalent or as a D-flip-flop/latch with enable allows for efficient use of the FPGA fabric. The VersaTile capability is unique to the Microsemi ProASIC family of third-generation architecture flash FPGAs. VersaTiles are connected with any of the four levels of routing hierarchy. Flash switches are distributed throughout the device to provide nonvolatile, reconfigurable interconnect programming. Maximum core utilization is possible for virtually any design.

### VersaTiles

The ProASIC3 core consists of VersaTiles, which have been enhanced beyond the ProASIC<sup>PLUS®</sup> core tiles. The ProASIC3 VersaTile supports the following:

- All 3-input logic functions—LUT-3 equivalent
- Latch with clear or set
- D-flip-flop with clear or set
- Enable D-flip-flop with clear or set

Refer to [Figure 1-3](#) for VersaTile configurations.

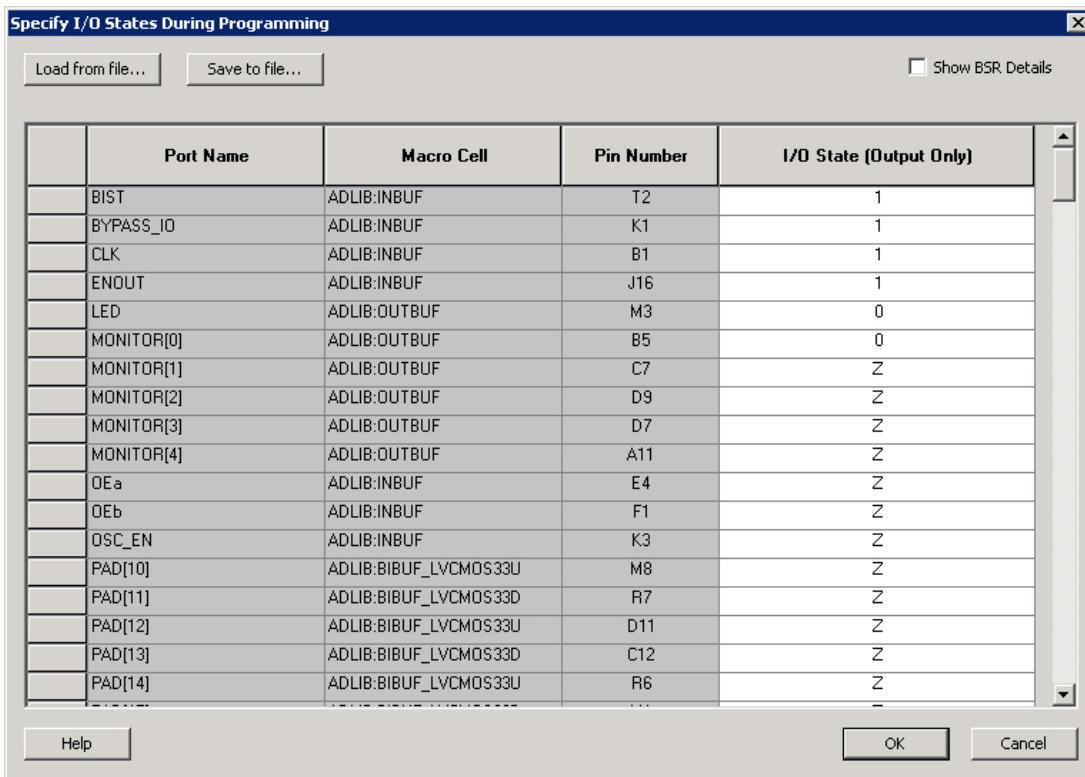


**Figure 1-3 • VersaTile Configurations**

0 – I/O is set to drive out logic Low

Last Known State – I/O is set to the last value that was driven out prior to entering the programming mode, and then held at that value during programming

Z -Tristate: I/O is tristated



**Figure 1-4 • I/O States During Programming Window**

6. Click OK to return to the FlashPoint – Programming File Generator window.

**Note:** I/O States During programming are saved to the ADB and resulting programming files after completing programming file generation.

**Table 2-2 • Recommended Operating Conditions<sup>1</sup>**

Symbol	Parameters <sup>1</sup>		Commercial	Industrial	Units
T <sub>J</sub>	Junction temperature		0 to 85 <sup>2</sup>	-40 to 100 <sup>2</sup>	°C
VCC <sup>3</sup>	1.5 V DC core supply voltage		1.425 to 1.575	1.425 to 1.575	V
VJTAG	JTAG DC voltage		1.4 to 3.6	1.4 to 3.6	V
VPUMP	Programming voltage	Programming Mode	3.15 to 3.45	3.15 to 3.45	V
		Operation <sup>4</sup>	0 to 3.6	0 to 3.6	V
VCCPLL	Analog power supply (PLL)		1.425 to 1.575	1.425 to 1.575	V
VCCI and VMV <sup>5</sup>	1.5 V DC supply voltage		1.425 to 1.575	1.425 to 1.575	V
	1.8 V DC supply voltage		1.7 to 1.9	1.7 to 1.9	V
	2.5 V DC supply voltage		2.3 to 2.7	2.3 to 2.7	V
	3.3 V DC supply voltage		3.0 to 3. <u>6</u>	3.0 to 3. <u>6</u>	V
	3.3 V wide range DC supply voltage <sup>6</sup>		2.7 to 3.6	2.7 to 3.6	V
	LVDS/B-LVDS/M-LVDS differential I/O		2.375 to 2.625	2.375 to 2.625	V
	LVPECL differential I/O		3.0 to 3.6	3.0 to 3.6	V

**Notes:**

1. All parameters representing voltages are measured with respect to GND unless otherwise specified.
2. Software Default Junction Temperature Range in the Libero® System-on-Chip (SoC) software is set to 0°C to +70°C for commercial, and -40°C to +85°C for industrial. To ensure targeted reliability standards are met across the full range of junction temperatures, Microsemi recommends using custom settings for temperature range before running timing and power analysis tools. For more information regarding custom settings, refer to the New Project Dialog Box in the [Libero SoC Online Help](#).
3. The ranges given here are for power supplies only. The recommended input voltage ranges specific to each I/O standard are given in [Table 2-18 on page 2-19](#).
4. VPUMP can be left floating during operation (not programming mode).
5. VMV and VCCI should be at the same voltage within a given I/O bank. VMV pins must be connected to the corresponding VCCI pins. See the "[VMVx I/O Supply Voltage \(quiet\)](#)" section on page 3-1 for further information.
6. 3.3 V wide range is compliant to the JESD8-B specification and supports 3.0 V VCCI operation.

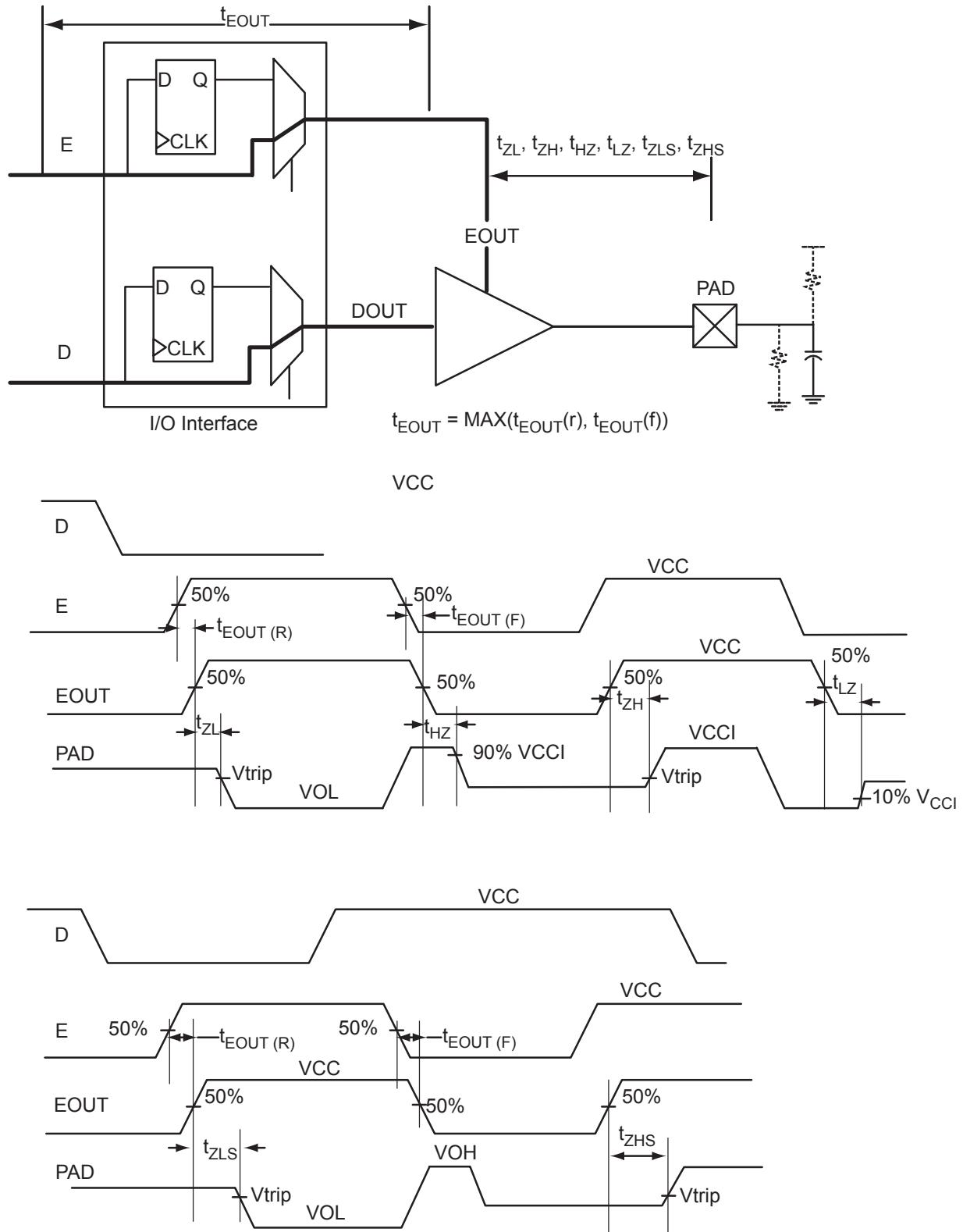


Figure 2-6 • Tristate Output Buffer Timing Model and Delays (Example)

## Summary of I/O Timing Characteristics – Default I/O Software Settings

**Table 2-22 • Summary of AC Measuring Points**

Standard	Measuring Trip Point ( $V_{trip}$ )
3.3 V LVTTL / 3.3 V LVCMOS	1.4 V
3.3 V LVCMOS Wide Range	1.4 V
2.5 V LVCMOS	1.2 V
1.8 V LVCMOS	0.90 V
1.5 V LVCMOS	0.75 V
3.3 V PCI	0.285 * VCCI (RR) 0.615 * VCCI (FF)
3.3 V PCI-X	0.285 * VCCI (RR) 0.615 * VCCI (FF)

**Table 2-23 • I/O AC Parameter Definitions**

Parameter	Parameter Definition
$t_{DP}$	Data to Pad delay through the Output Buffer
$t_{PY}$	Pad to Data delay through the Input Buffer
$t_{DOUT}$	Data to Output Buffer delay through the I/O interface
$t_{EOUT}$	Enable to Output Buffer Tristate Control delay through the I/O interface
$t_{DIN}$	Input Buffer to Data delay through the I/O interface
$t_{HZ}$	Enable to Pad delay through the Output Buffer—High to Z
$t_{ZH}$	Enable to Pad delay through the Output Buffer—Z to High
$t_{LZ}$	Enable to Pad delay through the Output Buffer—Low to Z
$t_{ZL}$	Enable to Pad delay through the Output Buffer—Z to Low
$t_{ZHS}$	Enable to Pad delay through the Output Buffer with delayed enable—Z to High
$t_{ZLS}$	Enable to Pad delay through the Output Buffer with delayed enable—Z to Low

## Timing Characteristics

**Table 2-50 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew**

Commercial-Case Conditions:  $T_J = 70^\circ\text{C}$ , Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V  
 Applicable to Advanced I/O Banks

Drive Strength	Equiv. Software Default Drive Strength Option <sup>1</sup>	Speed Grade	$t_{DOUT}$	$t_{DP}$	$t_{DIN}$	$t_{PY}$	$t_{EOUT}$	$t_{ZL}$	$t_{ZH}$	$t_{LZ}$	$t_{HZ}$	$t_{ZLS}$	$t_{ZHS}$	Units
100 $\mu\text{A}$	4 mA	Std.	0.60	11.84	0.04	1.02	0.43	11.84	10.00	4.10	4.04	15.23	13.40	ns
		-1	0.51	10.07	0.04	0.86	0.36	10.07	8.51	3.48	3.44	12.96	11.40	ns
		-2	0.45	8.84	0.03	0.76	0.32	8.84	7.47	3.06	3.02	11.38	10.00	ns
100 $\mu\text{A}$	6 mA	Std.	0.60	7.59	0.04	1.02	0.43	7.59	6.18	4.62	4.95	10.98	9.57	ns
		-1	0.51	6.45	0.04	0.86	0.36	6.45	5.25	3.93	4.21	9.34	8.14	ns
		-2	0.45	5.67	0.03	0.76	0.32	5.67	4.61	3.45	3.70	8.20	7.15	ns
100 $\mu\text{A}$	8 mA	Std.	0.60	7.59	0.04	1.02	0.43	7.59	6.18	4.62	4.95	10.98	9.57	ns
		-1	0.51	6.45	0.04	0.86	0.36	6.45	5.25	3.93	4.21	9.34	8.14	ns
		-2	0.45	5.67	0.03	0.76	0.32	5.67	4.61	3.45	3.70	8.20	7.15	ns
100 $\mu\text{A}$	12 mA	Std.	0.60	5.46	0.04	1.02	0.43	5.46	4.29	4.97	5.54	8.86	7.68	ns
		-1	0.51	4.65	0.04	0.86	0.36	4.65	3.65	4.22	4.71	7.53	6.54	ns
		-2	0.45	4.08	0.03	0.76	0.32	4.08	3.20	3.71	4.14	6.61	5.74	ns
100 $\mu\text{A}$	16 mA	Std.	0.60	5.15	0.04	1.02	0.43	5.15	3.89	5.04	5.69	8.55	7.29	ns
		-1	0.51	4.38	0.04	0.86	0.36	4.38	3.31	4.29	4.84	7.27	6.20	ns
		-2	0.45	3.85	0.03	0.76	0.32	3.85	2.91	3.77	4.25	6.38	5.44	ns
100 $\mu\text{A}$	24 mA	Std.	0.60	4.75	0.04	1.02	0.43	4.75	3.22	5.14	6.28	8.15	6.61	ns
		-1	0.51	4.04	0.04	0.86	0.36	4.04	2.74	4.37	5.34	6.93	5.62	ns
		-2	0.45	3.55	0.03	0.76	0.32	3.55	2.40	3.84	4.69	6.09	4.94	ns

**Notes:**

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is  $\pm 100 \mu\text{A}$ . Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. Software default selection highlighted in gray.
3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

**Table 2-53 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew**

 Commercial-Case Conditions:  $T_J = 70^\circ\text{C}$ , Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V  
 Applicable to Standard Plus I/O Banks

Drive Strength	Equiv. Software Default Drive Strength Option <sup>1</sup>	Speed Grade	$t_{DOUT}$	$t_{DP}$	$t_{DIN}$	$t_{PY}$	$t_{EOUT}$	$t_{ZL}$	$t_{ZH}$	$t_{LZ}$	$t_{HZ}$	$t_{ZLS}$	$t_{ZHS}$	Units
100 $\mu\text{A}$	2 mA	Std.	0.60	14.97	0.04	1.52	0.43	14.97	12.79	3.52	3.41	18.36	16.18	ns
		-1	0.51	12.73	0.04	1.29	0.36	12.73	10.88	2.99	2.90	15.62	13.77	ns
		-2	0.45	11.18	0.03	1.14	0.32	11.18	9.55	2.63	2.55	13.71	12.08	ns
100 $\mu\text{A}$	4 mA	Std.	0.60	10.36	0.04	1.52	0.43	10.36	8.93	3.99	4.24	13.75	12.33	ns
		-1	0.51	8.81	0.04	1.29	0.36	8.81	7.60	3.39	3.60	11.70	10.49	ns
		-2	0.45	7.74	0.03	1.14	0.32	7.74	6.67	2.98	3.16	10.27	9.21	ns
100 $\mu\text{A}$	6 mA	Std.	0.60	10.36	0.04	1.52	0.43	10.36	8.93	3.99	4.24	13.75	12.33	ns
		-1	0.51	8.81	0.04	1.29	0.36	8.81	7.60	3.39	3.60	11.70	10.49	ns
		-2	0.45	7.74	0.03	1.14	0.32	7.74	6.67	2.98	3.16	10.27	9.21	ns
100 $\mu\text{A}$	8 mA	Std.	0.60	7.81	0.04	1.52	0.43	7.81	6.85	4.32	4.76	11.20	10.24	ns
		-1	0.51	6.64	0.04	1.29	0.36	6.64	5.82	3.67	4.05	9.53	8.71	ns
		-2	0.45	5.83	0.03	1.14	0.32	5.83	5.11	3.22	3.56	8.36	7.65	ns
100 $\mu\text{A}$	16 mA	Std.	0.60	7.81	0.04	1.52	0.43	7.81	6.85	4.32	4.76	11.20	10.24	ns
		-1	0.51	6.64	0.04	1.29	0.36	6.64	5.82	3.67	4.05	9.53	8.71	ns
		-2	0.45	5.83	0.03	1.14	0.32	5.83	5.11	3.22	3.56	8.36	7.65	ns

**Notes:**

1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is  $\pm 100 \mu\text{A}$ . Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

**Table 2-77 • Minimum and Maximum DC Input and Output Levels  
Applicable to Standard Plus I/O Banks**

1.5 V LVC MOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL <sup>1</sup>	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	µA <sup>4</sup>	µA <sup>4</sup>
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.575	0.25 * VCCI	0.75 * VCCI	2	2	16	13	10	10
4 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.575	0.25 * VCCI	0.75 * VCCI	4	4	33	25	10	10

**Notes:**

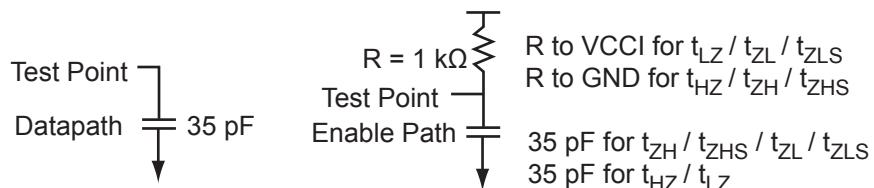
1. *IIL* is the input leakage current per I/O pin over recommended operation conditions where  $-0.3 \text{ V} < \text{VIN} < \text{VIL}$ .
2. *IIH* is the input leakage current per I/O pin over recommended operating conditions  $\text{VIH} < \text{VIN} < \text{VCCI}$ . Input current is larger when operating outside recommended ranges
3. Currents are measured at high temperature ( $100^\circ\text{C}$  junction temperature) and maximum voltage.
4. Currents are measured at  $85^\circ\text{C}$  junction temperature.
5. Software default selection highlighted in gray.

**Table 2-78 • Minimum and Maximum DC Input and Output Levels  
Applicable to Standard I/O Banks**

1.5 V LVC MOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL <sup>1</sup>	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	µA <sup>4</sup>	µA <sup>4</sup>
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	2	2	13	16	10	10

**Notes:**

1. *IIL* is the input leakage current per I/O pin over recommended operation conditions where  $-0.3 \text{ V} < \text{VIN} < \text{VIL}$ .
2. *IIH* is the input leakage current per I/O pin over recommended operating conditions  $\text{VIH} < \text{VIN} < \text{VCCI}$ . Input current is larger when operating outside recommended ranges.
3. Currents are measured at high temperature ( $100^\circ\text{C}$  junction temperature) and maximum voltage.
4. Currents are measured at  $85^\circ\text{C}$  junction temperature.
5. Software default selection highlighted in gray.



**Figure 2-10 • AC Loading**

**Table 2-79 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	C <sub>LOAD</sub> (pF)
0	1.5	0.75	35

Note: \*Measuring point =  $V_{trip}$ . See Table 2-22 on page 2-22 for a complete table of trip points.

## Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

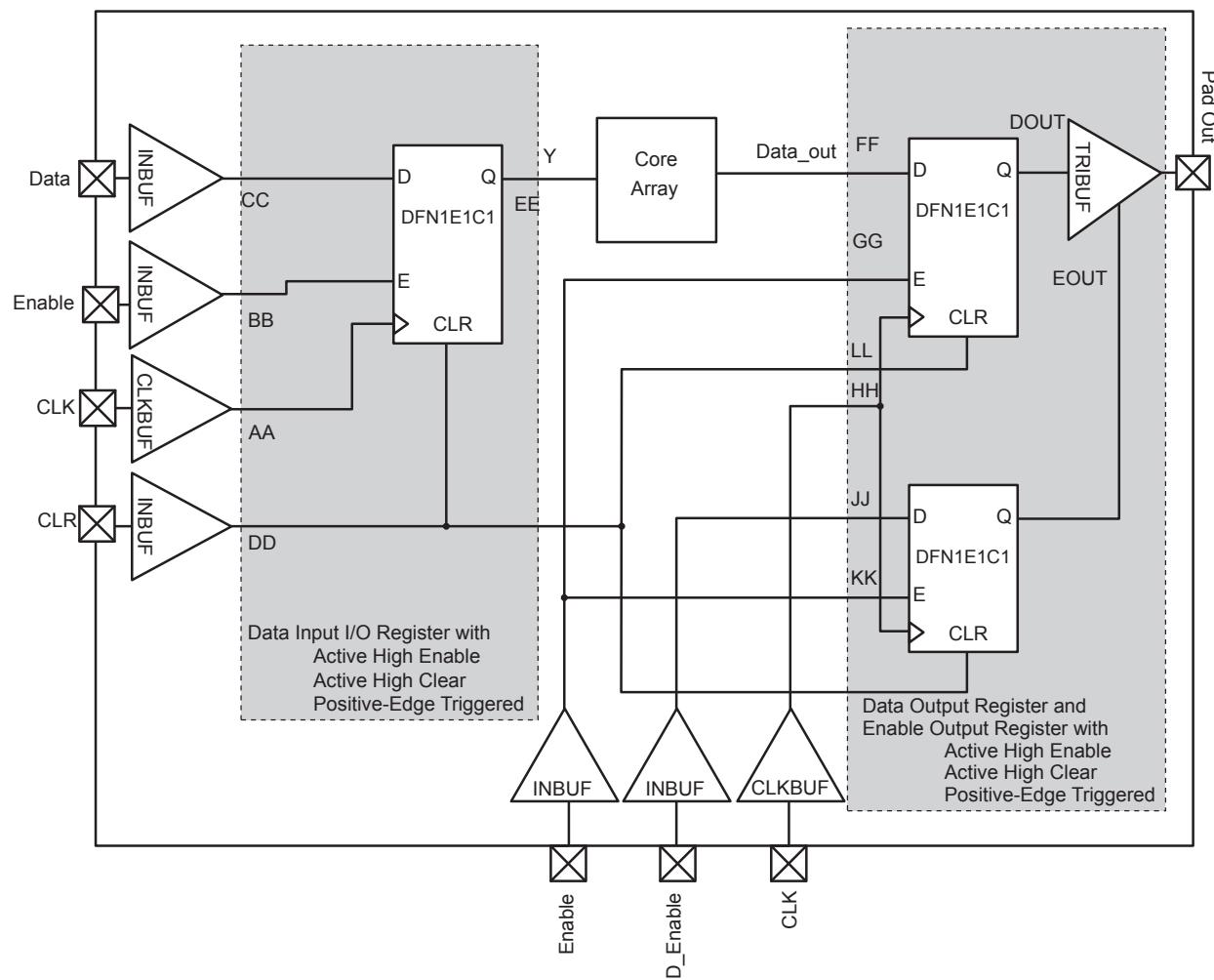


Figure 2-16 • Timing Model of the Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

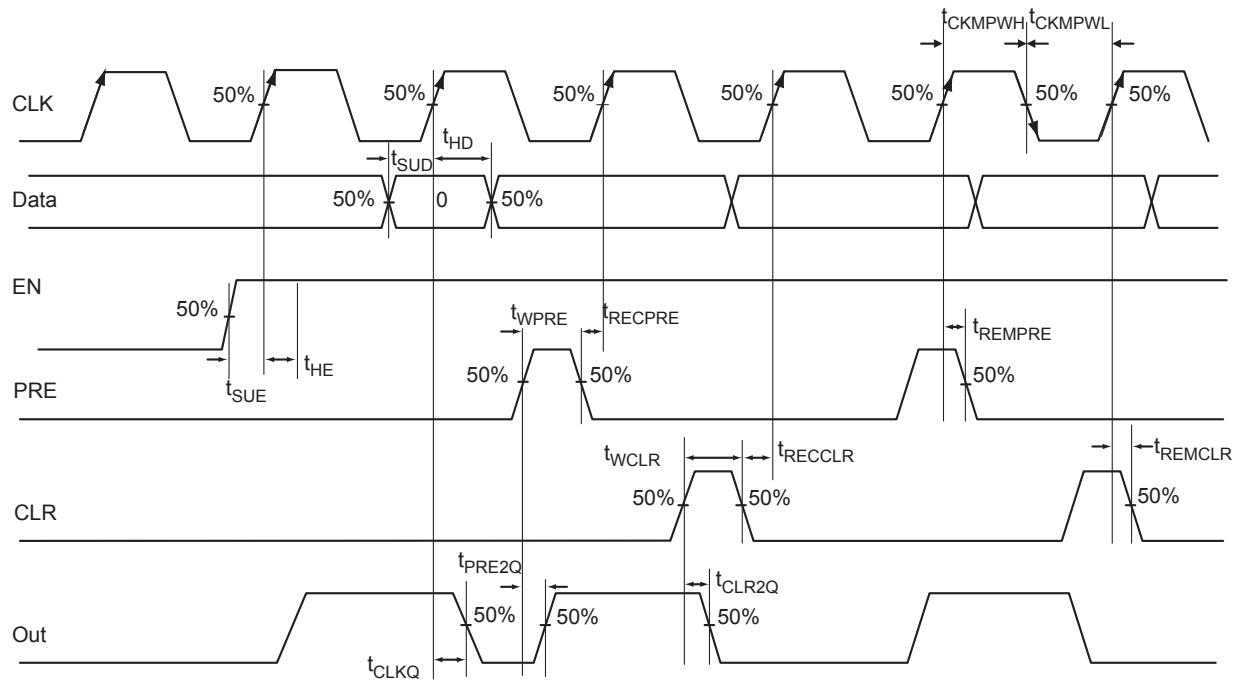


Figure 2-27 • Timing Model and Waveforms

### Timing Characteristics

Table 2-106 • Register Delays

Commercial-Case Conditions:  $T_J = 70^\circ\text{C}$ , Worst-Case VCC = 1.425 V

Parameter	Description	-2	-1	Std.	Units
t <sub>CLKQ</sub>	Clock-to-Q of the Core Register	0.55	0.63	0.74	ns
t <sub>SUD</sub>	Data Setup Time for the Core Register	0.43	0.49	0.57	ns
t <sub>HD</sub>	Data Hold Time for the Core Register	0.00	0.00	0.00	ns
t <sub>SUE</sub>	Enable Setup Time for the Core Register	0.45	0.52	0.61	ns
t <sub>HE</sub>	Enable Hold Time for the Core Register	0.00	0.00	0.00	ns
t <sub>CLR2Q</sub>	Asynchronous Clear-to-Q of the Core Register	0.40	0.45	0.53	ns
t <sub>PRE2Q</sub>	Asynchronous Preset-to-Q of the Core Register	0.40	0.45	0.53	ns
t <sub>REMCLR</sub>	Asynchronous Clear Removal Time for the Core Register	0.00	0.00	0.00	ns
t <sub>RECCLR</sub>	Asynchronous Clear Recovery Time for the Core Register	0.22	0.25	0.30	ns
t <sub>REMPRE</sub>	Asynchronous Preset Removal Time for the Core Register	0.00	0.00	0.00	ns
t <sub>RECPRE</sub>	Asynchronous Preset Recovery Time for the Core Register	0.22	0.25	0.30	ns
t <sub>WCLR</sub>	Asynchronous Clear Minimum Pulse Width for the Core Register	0.22	0.25	0.30	ns
t <sub>WPRE</sub>	Asynchronous Preset Minimum Pulse Width for the Core Register	0.22	0.25	0.30	ns
t <sub>CKMPWH</sub>	Clock Minimum Pulse Width High for the Core Register	0.32	0.37	0.43	ns
t <sub>CKMPWL</sub>	Clock Minimum Pulse Width Low for the Core Register	0.36	0.41	0.48	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

**Table 2-122 • A3P250 FIFO 2k×2**  
**Worst Commercial-Case Conditions:  $T_J = 70^\circ\text{C}$ , VCC = 1.425 V**

Parameter	Description	-2	-1	Std.	Units
$t_{ENS}$	REN, WEN Setup Time	4.39	5.00	5.88	ns
$t_{ENH}$	REN, WEN Hold Time	0.00	0.00	0.00	ns
$t_{BKS}$	BLK Setup Time	0.19	0.22	0.26	ns
$t_{BKH}$	BLK Hold Time	0.00	0.00	0.00	ns
$t_{DS}$	Input Data (WD) Setup Time	0.18	0.21	0.25	ns
$t_{DH}$	Input Data (WD) Hold Time	0.00	0.00	0.00	ns
$t_{CKQ1}$	Clock High to New Data Valid on RD (flow-through)	2.36	2.68	3.15	ns
$t_{CKQ2}$	Clock High to New Data Valid on RD (pipelined)	0.89	1.02	1.20	ns
$t_{RCKEF}$	RCLK High to Empty Flag Valid	1.72	1.96	2.30	ns
$t_{WCKFF}$	WCLK High to Full Flag Valid	1.63	1.86	2.18	ns
$t_{CKAF}$	Clock High to Almost Empty/Full Flag Valid	6.19	7.05	8.29	ns
$t_{RSTFG}$	RESET Low to Empty/Full Flag Valid	1.69	1.93	2.27	ns
$t_{RSTAF}$	RESET Low to Almost Empty/Full Flag Valid	6.13	6.98	8.20	ns
$t_{RSTBQ}$	RESET Low to Data Out Low on RD (flow-through)	0.92	1.05	1.23	ns
	RESET Low to Data Out Low on RD (pipelined)	0.92	1.05	1.23	ns
$t_{REMRSTB}$	RESET Removal	0.29	0.33	0.38	ns
$t_{RECRSTB}$	RESET Recovery	1.50	1.71	2.01	ns
$t_{MPWRSTB}$	RESET Minimum Pulse Width	0.21	0.24	0.29	ns
$t_{CYC}$	Clock Cycle Time	3.23	3.68	4.32	ns
$F_{MAX}$	Maximum Frequency for FIFO	310	272	231	MHz

**Table 2-123 • A3P250 FIFO 4k×1**  
**Worst Commercial-Case Conditions:  $T_J = 70^\circ\text{C}$ , VCC = 1.425 V**

Parameter	Description	-2	-1	Std.	Units
$t_{ENS}$	REN, WEN Setup Time	4.86	5.53	6.50	ns
$t_{ENH}$	REN, WEN Hold Time	0.00	0.00	0.00	ns
$t_{BKS}$	BLK Setup Time	0.19	0.22	0.26	ns
$t_{BKH}$	BLK Hold Time	0.00	0.00	0.00	ns
$t_{DS}$	Input Data (WD) Setup Time	0.18	0.21	0.25	ns
$t_{DH}$	Input Data (WD) Hold Time	0.00	0.00	0.00	ns
$t_{CKQ1}$	Clock High to New Data Valid on RD (flow-through)	2.36	2.68	3.15	ns
$t_{CKQ2}$	Clock High to New Data Valid on RD (pipelined)	0.89	1.02	1.20	ns
$t_{RCKEF}$	RCLK High to Empty Flag Valid	1.72	1.96	2.30	ns
$t_{WCKFF}$	WCLK High to Full Flag Valid	1.63	1.86	2.18	ns
$t_{CKAF}$	Clock High to Almost Empty/Full Flag Valid	6.19	7.05	8.29	ns
$t_{RSTFG}$	RESET Low to Empty/Full Flag Valid	1.69	1.93	2.27	ns

mode is not used in the design, the FF pin is available as a regular I/O. For IGLOOe, ProASIC3EL, and RT ProASIC3 only, the FF pin can be configured as a Schmitt trigger input.

When Flash\*Freeze mode is used, the FF pin must not be left floating to avoid accidentally entering Flash\*Freeze mode. While in Flash\*Freeze mode, the Flash\*Freeze pin should be constantly asserted.

The Flash\*Freeze pin can be used with any single-ended I/O standard supported by the I/O bank in which the pin is located, and input signal levels compatible with the I/O standard selected. The FF pin should be treated as a sensitive asynchronous signal. When defining pin placement and board layout, simultaneously switching outputs (SSOs) and their effects on sensitive asynchronous pins must be considered.

Unused FF or I/O pins are tristated with weak pull-up. This default configuration applies to both Flash\*Freeze mode and normal operation mode. No user intervention is required.

## JTAG Pins

Low power flash devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). VCC must also be powered for the JTAG state machine to operate, even if the device is in bypass mode; VJTAG alone is insufficient. Both VJTAG and VCC to the part must be supplied to allow JTAG signals to transition the device. Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND.

### TCK                    Test Clock

Test clock input for JTAG boundary scan, ISP, and UJTAG. The TCK pin does not have an internal pull-up/-down resistor. If JTAG is not used, Microsemi recommends tying off TCK to GND through a resistor placed close to the FPGA pin. This prevents JTAG operation in case TMS enters an undesired state.

Note that to operate at all VJTAG voltages, 500 Ω to 1 kΩ will satisfy the requirements. Refer to [Table 1](#) for more information.

**Table 1 • Recommended Tie-Off Values for the TCK and TRST Pins**

VJTAG	Tie-Off Resistance
3.3 V	200 Ω – 1 kΩ
2.5 V	200 Ω – 1 kΩ
1.8 V	500 Ω – 1 kΩ
1.5 V	500 Ω – 1 kΩ

*Notes:*

1. *Equivalent parallel resistance if more than one device is on the JTAG chain*
2. *The TCK pin can be pulled up/down.*
3. *The TRST pin is pulled down.*

### TDI                    Test Data Input

Serial input for JTAG boundary scan, ISP, and UJTAG usage. There is an internal weak pull-up resistor on the TDI pin.

### TDO                    Test Data Output

Serial output for JTAG boundary scan, ISP, and UJTAG usage.

### TMS                    Test Mode Select

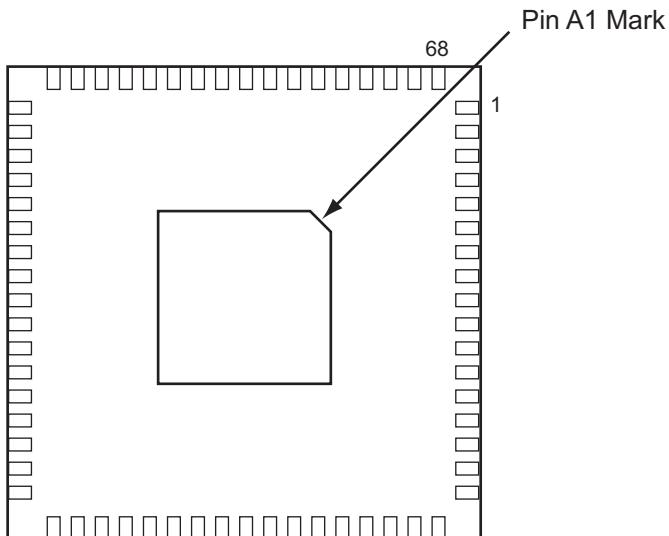
The TMS pin controls the use of the IEEE 1532 boundary scan pins (TCK, TDI, TDO, TRST). There is an internal weak pull-up resistor on the TMS pin.

### TRST                    Boundary Scan Reset Pin

The TRST pin functions as an active low input to asynchronously initialize (or reset) the boundary scan circuitry. There is an internal weak pull-up resistor on the TRST pin. If JTAG is not used, an external pull-down resistor could be included to ensure the test access port (TAP) is held in reset mode. The resistor values must be chosen from [Table 1](#) and must satisfy the parallel resistance value requirement. The values in [Table 1](#) correspond to the resistor recommended when a single device is used, and the equivalent parallel resistor when multiple devices are connected via a JTAG chain.

## QN68 – Bottom View

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**Note:** *The die attach paddle center of the package is tied to ground (GND).*

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### Note

For more information on package drawings, see [PD3068: Package Mechanical Drawings](#).

QN132	
Pin Number	A3P125 Function
A1	GAB2/IO69RSB1
A2	IO130RSB1
A3	VCCIB1
A4	GFC1/IO126RSB1
A5	GFB0/IO123RSB1
A6	VCCPLF
A7	GFA1/IO121RSB1
A8	GFC2/IO118RSB1
A9	IO115RSB1
A10	VCC
A11	GEB1/IO110RSB1
A12	GEA0/IO107RSB1
A13	GEC2/IO104RSB1
A14	IO100RSB1
A15	VCC
A16	IO99RSB1
A17	IO96RSB1
A18	IO94RSB1
A19	IO91RSB1
A20	IO85RSB1
A21	IO79RSB1
A22	VCC
A23	GDB2/IO71RSB1
A24	TDI
A25	TRST
A26	GDC1/IO61RSB0
A27	VCC
A28	IO60RSB0
A29	GCC2/IO59RSB0
A30	GCA2/IO57RSB0
A31	GCA0/IO56RSB0
A32	GCB1/IO53RSB0
A33	IO49RSB0
A34	VCC
A35	IO44RSB0
A36	GBA2/IO41RSB0

QN132	
Pin Number	A3P125 Function
A37	GBB1/IO38RSB0
A38	GBC0/IO35RSB0
A39	VCCIB0
A40	IO28RSB0
A41	IO22RSB0
A42	IO18RSB0
A43	IO14RSB0
A44	IO11RSB0
A45	IO07RSB0
A46	VCC
A47	GAC1/IO05RSB0
A48	GAB0/IO02RSB0
B1	IO68RSB1
B2	GAC2/IO131RSB1
B3	GND
B4	GFC0/IO125RSB1
B5	VCOMPLF
B6	GND
B7	GFB2/IO119RSB1
B8	IO116RSB1
B9	GND
B10	GEB0/IO109RSB1
B11	VMV1
B12	GEB2/IO105RSB1
B13	IO101RSB1
B14	GND
B15	IO98RSB1
B16	IO95RSB1
B17	GND
B18	IO87RSB1
B19	IO81RSB1
B20	GND
B21	GNDQ
B22	TMS
B23	TDO
B24	GDC0/IO62RSB0

QN132	
Pin Number	A3P125 Function
B25	GND
B26	NC
B27	GCB2/IO58RSB0
B28	GND
B29	GCB0/IO54RSB0
B30	GCC1/IO51RSB0
B31	GND
B32	GBB2/IO43RSB0
B33	VMV0
B34	GBA0/IO39RSB0
B35	GBC1/IO36RSB0
B36	GND
B37	IO26RSB0
B38	IO21RSB0
B39	GND
B40	IO13RSB0
B41	IO08RSB0
B42	GND
B43	GAC0/IO04RSB0
B44	GNDQ
C1	GAA2/IO67RSB1
C2	IO132RSB1
C3	VCC
C4	GFB1/IO124RSB1
C5	GFA0/IO122RSB1
C6	GFA2/IO120RSB1
C7	IO117RSB1
C8	VCCIB1
C9	GEA1/IO108RSB1
C10	GNDQ
C11	GEA2/IO106RSB1
C12	IO103RSB1
C13	VCCIB1
C14	IO97RSB1
C15	IO93RSB1
C16	IO89RSB1

<b>QN132</b>	
<b>Pin Number</b>	<b>A3P125 Function</b>
C17	IO83RSB1
C18	VCCIB1
C19	TCK
C20	VMV1
C21	VPUMP
C22	VJTAG
C23	VCCIB0
C24	NC
C25	NC
C26	GCA1/IO55RSB0
C27	GCC0/IO52RSB0
C28	VCCIB0
C29	IO42RSB0
C30	GNDQ
C31	GBA1/IO40RSB0
C32	GBB0/IO37RSB0
C33	VCC
C34	IO24RSB0
C35	IO19RSB0
C36	IO16RSB0
C37	IO10RSB0
C38	VCCIB0
C39	GAB1/IO03RSB0
C40	VMV0
D1	GND
D2	GND
D3	GND
D4	GND

CS121	
Pin Number	A3P060 Function
K10	VPUMP
K11	GDB1/IO47RSB0
L1	VMV1
L2	GNDQ
L3	IO65RSB1
L4	IO63RSB1
L5	IO61RSB1
L6	IO58RSB1
L7	IO57RSB1
L8	IO55RSB1
L9	GNDQ
L10	GDA0/IO50RSB0
L11	VMV1

TQ144	
Pin Number	A3P060 Function
1	GAA2/IO51RSB1
2	IO52RSB1
3	GAB2/IO53RSB1
4	IO95RSB1
5	GAC2/IO94RSB1
6	IO93RSB1
7	IO92RSB1
8	IO91RSB1
9	VCC
10	GND
11	VCCIB1
12	IO90RSB1
13	GFC1/IO89RSB1
14	GFC0/IO88RSB1
15	GFB1/IO87RSB1
16	GFB0/IO86RSB1
17	VCOMPLF
18	GFA0/IO85RSB1
19	VCCPLF
20	GFA1/IO84RSB1
21	GFA2/IO83RSB1
22	GFB2/IO82RSB1
23	GFC2/IO81RSB1
24	IO80RSB1
25	IO79RSB1
26	IO78RSB1
27	GND
28	VCCIB1
29	GEC1/IO77RSB1
30	GEC0/IO76RSB1
31	GEB1/IO75RSB1
32	GEB0/IO74RSB1
33	GEA1/IO73RSB1
34	GEA0/IO72RSB1
35	VMV1
36	GNDQ

TQ144	
Pin Number	A3P060 Function
37	NC
38	GEA2/IO71RSB1
39	GEB2/IO70RSB1
40	GEC2/IO69RSB1
41	IO68RSB1
42	IO67RSB1
43	IO66RSB1
44	IO65RSB1
45	VCC
46	GND
47	VCCIB1
48	NC
49	IO64RSB1
50	NC
51	IO63RSB1
52	NC
53	IO62RSB1
54	NC
55	IO61RSB1
56	NC
57	NC
58	IO60RSB1
59	IO59RSB1
60	IO58RSB1
61	IO57RSB1
62	NC
63	GND
64	NC
65	GDC2/IO56RSB1
66	GDB2/IO55RSB1
67	GDA2/IO54RSB1
68	GNDQ
69	TCK
70	TDI
71	TMS
72	VMV1

TQ144	
Pin Number	A3P060 Function
73	VPUMP
74	NC
75	TDO
76	TRST
77	VJTAG
78	GDA0/IO50RSB0
79	GDB0/IO48RSB0
80	GDB1/IO47RSB0
81	VCCIB0
82	GND
83	IO44RSB0
84	GCC2/IO43RSB0
85	GCB2/IO42RSB0
86	GCA2/IO41RSB0
87	GCA0/IO40RSB0
88	GCA1/IO39RSB0
89	GCB0/IO38RSB0
90	GCB1/IO37RSB0
91	GCC0/IO36RSB0
92	GCC1/IO35RSB0
93	IO34RSB0
94	IO33RSB0
95	NC
96	NC
97	NC
98	VCCIB0
99	GND
100	VCC
101	IO30RSB0
102	GBC2/IO29RSB0
103	IO28RSB0
104	GBB2/IO27RSB0
105	IO26RSB0
106	GBA2/IO25RSB0
107	VMV0
108	GNDQ

<b>PQ208</b>	
<b>Pin Number</b>	<b>A3P250 Function</b>
109	TRST
110	VJTAG
111	GDA0/IO60VDB1
112	GDA1/IO60UDB1
113	GDB0/IO59VDB1
114	GDB1/IO59UDB1
115	GDC0/IO58VDB1
116	GDC1/IO58UDB1
117	IO57VDB1
118	IO57UDB1
119	IO56NDB1
120	IO56PDB1
121	IO55RSB1
122	GND
123	VCCIB1
124	NC
125	NC
126	VCC
127	IO53NDB1
128	GCC2/IO53PDB1
129	GCB2/IO52PSB1
130	GND
131	GCA2/IO51PSB1
132	GCA1/IO50PDB1
133	GCA0/IO50NDB1
134	GCB0/IO49NDB1
135	GCB1/IO49PDB1
136	GCC0/IO48NDB1
137	GCC1/IO48PDB1
138	IO47NDB1
139	IO47PDB1
140	VCCIB1
141	GND
142	VCC
143	IO46RSB1
144	IO45NDB1

<b>PQ208</b>	
<b>Pin Number</b>	<b>A3P250 Function</b>
145	IO45PDB1
146	IO44NDB1
147	IO44PDB1
148	IO43NDB1
149	GBC2/IO43PDB1
150	IO42NDB1
151	GBB2/IO42PDB1
152	IO41NDB1
153	GBA2/IO41PDB1
154	VMV1
155	GNDQ
156	GND
157	NC
158	GBA1/IO40RSB0
159	GBA0/IO39RSB0
160	GBB1/IO38RSB0
161	GBB0/IO37RSB0
162	GND
163	GBC1/IO36RSB0
164	GBC0/IO35RSB0
165	IO34RSB0
166	IO33RSB0
167	IO32RSB0
168	IO31RSB0
169	IO30RSB0
170	VCCIB0
171	VCC
172	IO29RSB0
173	IO28RSB0
174	IO27RSB0
175	IO26RSB0
176	IO25RSB0
177	IO24RSB0
178	GND
179	IO23RSB0
180	IO22RSB0

<b>PQ208</b>	
<b>Pin Number</b>	<b>A3P250 Function</b>
181	IO21RSB0
182	IO20RSB0
183	IO19RSB0
184	IO18RSB0
185	IO17RSB0
186	VCCIB0
187	VCC
188	IO16RSB0
189	IO15RSB0
190	IO14RSB0
191	IO13RSB0
192	IO12RSB0
193	IO11RSB0
194	IO10RSB0
195	GND
196	IO09RSB0
197	IO08RSB0
198	IO07RSB0
199	IO06RSB0
200	VCCIB0
201	GAC1/IO05RSB0
202	GAC0/IO04RSB0
203	GAB1/IO03RSB0
204	GAB0/IO02RSB0
205	GAA1/IO01RSB0
206	GAA0/IO00RSB0
207	GNDQ
208	VMV0

<b>FG144</b>	
<b>Pin Number</b>	<b>A3P250 Function</b>
A1	GNDQ
A2	VMV0
A3	GAB0/IO02RSB0
A4	GAB1/IO03RSB0
A5	IO16RSB0
A6	GND
A7	IO29RSB0
A8	VCC
A9	IO33RSB0
A10	GBA0/IO39RSB0
A11	GBA1/IO40RSB0
A12	GNDQ
B1	GAB2/IO117UDB3
B2	GND
B3	GAA0/IO00RSB0
B4	GAA1/IO01RSB0
B5	IO14RSB0
B6	IO19RSB0
B7	IO22RSB0
B8	IO30RSB0
B9	GBB0/IO37RSB0
B10	GBB1/IO38RSB0
B11	GND
B12	VMV1
C1	IO117VDB3
C2	GFA2/IO107PPB3
C3	GAC2/IO116UDB3
C4	VCC
C5	IO12RSB0
C6	IO17RSB0
C7	IO24RSB0
C8	IO31RSB0
C9	IO34RSB0
C10	GBA2/IO41PDB1
C11	IO41NDB1
C12	GBC2/IO43PPB1

<b>FG144</b>	
<b>Pin Number</b>	<b>A3P250 Function</b>
D1	IO112NDB3
D2	IO112PDB3
D3	IO116VDB3
D4	GAA2/IO118UPB3
D5	GAC0/IO04RSB0
D6	GAC1/IO05RSB0
D7	GBC0/IO35RSB0
D8	GBC1/IO36RSB0
D9	GBB2/IO42PDB1
D10	IO42NDB1
D11	IO43NPB1
D12	GCB1/IO49PPB1
E1	VCC
E2	GFC0/IO110NDB3
E3	GFC1/IO110PDB3
E4	VCCIB3
E5	IO118VPB3
E6	VCCIB0
E7	VCCIB0
E8	GCC1/IO48PDB1
E9	VCCIB1
E10	VCC
E11	GCA0/IO50NDB1
E12	IO51NDB1
F1	GFB0/IO109NPB3
F2	VCOMPLF
F3	GFB1/IO109PPB3
F4	IO107NPB3
F5	GND
F6	GND
F7	GND
F8	GCC0/IO48NDB1
F9	GCB0/IO49NPB1
F10	GND
F11	GCA1/IO50PDB1
F12	GCA2/IO51PDB1

<b>FG144</b>	
<b>Pin Number</b>	<b>A3P250 Function</b>
G1	GFA1/IO108PPB3
G2	GND
G3	VCCPLF
G4	GFA0/IO108NPB3
G5	GND
G6	GND
G7	GND
G8	GDC1/IO58UPB1
G9	IO53NDB1
G10	GCC2/IO53PDB1
G11	IO52NDB1
G12	GCB2/IO52PDB1
H1	VCC
H2	GFB2/IO106PDB3
H3	GFC2/IO105PSB3
H4	GEC1/IO100PDB3
H5	VCC
H6	IO79RSB2
H7	IO65RSB2
H8	GDB2/IO62RSB2
H9	GDC0/IO58VPB1
H10	VCCIB1
H11	IO54PSB1
H12	VCC
J1	GEB1/IO99PDB3
J2	IO106NDB3
J3	VCCIB3
J4	GEC0/IO100NDB3
J5	IO88RSB2
J6	IO81RSB2
J7	VCC
J8	TCK
J9	GDA2/IO61RSB2
J10	TDO
J11	GDA1/IO60UDB1
J12	GDB1/IO59UDB1

<b>FG256</b>	
<b>Pin Number</b>	<b>A3P250 Function</b>
P9	IO76RSB2
P10	IO71RSB2
P11	IO66RSB2
P12	NC
P13	TCK
P14	VPUMP
P15	TRST
P16	GDA0/IO60VDB1
R1	GEA1/IO98PDB3
R2	GEA0/IO98NDB3
R3	NC
R4	GEC2/IO95RSB2
R5	IO91RSB2
R6	IO88RSB2
R7	IO84RSB2
R8	IO80RSB2
R9	IO77RSB2
R10	IO72RSB2
R11	IO68RSB2
R12	IO65RSB2
R13	GDB2/IO62RSB2
R14	TDI
R15	NC
R16	TDO
T1	GND
T2	IO94RSB2
T3	GEB2/IO96RSB2
T4	IO93RSB2
T5	IO90RSB2
T6	IO87RSB2
T7	IO83RSB2
T8	IO79RSB2
T9	IO78RSB2
T10	IO73RSB2
T11	IO70RSB2
T12	GDC2/IO63RSB2

<b>FG256</b>	
<b>Pin Number</b>	<b>A3P250 Function</b>
T13	IO67RSB2
T14	GDA2/IO61RSB2
T15	TMS
T16	GND